

EDO/FP DIMM/SIMM/SODIMM (Old Code)

K M M X X X X X X X X X X X X X X - X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20

1~2. Samsung Memory (KM)

3. Module Module (M)

4. Memory Type & Edge connector

3 : DRAM DIMM 4 : DRAM 8 byte SODIMM
 5 : DRAM SIMM

5~6. Organization

32 / 36 : x32 / x36 bit 64 / 72 : x64 / x72 bit

7. Process & Operating Voltage

Blank : CMOS 5V V : CMOS 3.3V

8~9. Depth

32 : 32M 16 : 16M
 8 : 8M 4 : 4M

10. Refresh

0 : 4K Cycle 1 : 2K Cycle
 2 : 1K Cycle 8 : 8K Cycle

11. Power

0 : Normal
 2 : Low Power & Self Refresh

12. Operation & Organization

0 : F/P 3 : Using Quad CAS
 4 : Using EDO 5 : Using EDO & Quad CAS

13. Component Revision

Blank : None A : 1st Rev.
 B : 2nd Rev. C : 3rd Rev.

14. Package Type

Blank : SOJ (1st) K : SOJ (2nd)
 T : TSOP (1st) S : TSOP (2nd)

15. PCB Revision

Blank : None 1 : 1st Rev.
 2 : 2nd Rev. 3 : 3rd Rev.

16. Number of Components

Blank : More than 7 chips
 W : Word wide base
 U : Byte wide base

17. Only x32 or x33 PCB

V : x32 or x33 PCB

18. Lead Finish & Customer

Blank : Solder G : Gold
 D : DEC H : HP
 M : IBM P : Nickel
 Q : Compaq X : Cambex

19. "—"

20. Speed

5 : 50ns 6 : 60ns